

CMS05

Switching Mode Power Supply Applications
 Portable Equipment Battery Applications

- Repetitive peak reverse voltage : $V_{RRM} = 30\text{ V}$
- Average forward current : $I_F (AV) = 5\text{ A}$
- Peak forward voltage : $V_{FM} = 0.45\text{ V (max)}$
- Suitable for compact assembly due to small surface-mount package
 "M-FLAT™" (Toshiba package name)

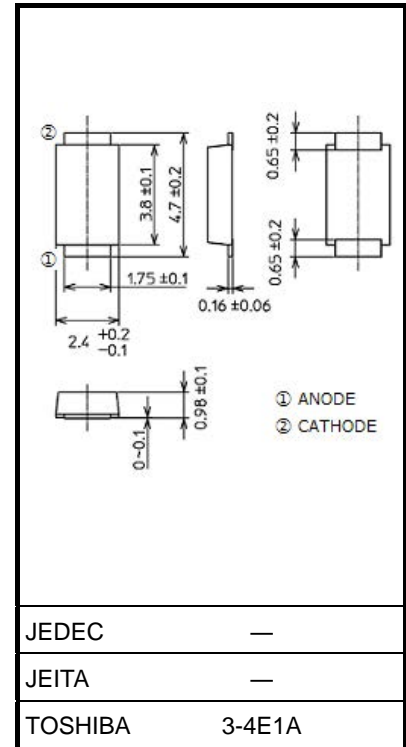
Absolute Maximum Ratings (Ta = 25°C)

Characteristics	Symbol	Rating	Unit
Repetitive peak reverse voltage	V_{RRM}	30	V
Average forward current	$I_F (AV)$	5 (Note 1)	A
Non-repetitive peak forward surge current	I_{FSM}	70 (50 Hz)	A
Junction temperature	T_j	-40 to 150	°C
Storage temperature	T_{stg}	-40 to 150	°C

Note 1: $T_l = 100^\circ\text{C}$ Device mounted on a ceramic board
 Board size : 50 mm × 50 mm
 Soldering land size : 2 mm × 2 mm
 Board thickness : 0.64 mm
 Rectangular waveform ($\alpha = 180^\circ$), $V_R = 15\text{ V}$

Note: Using continuously under heavy loads (e.g. the application of high temperature/current/voltage and the significant change in temperature, etc.) may cause this product to decrease in the reliability significantly even if the operating conditions (i.e. operating temperature/current/voltage, etc.) are within the absolute maximum ratings. Please design the appropriate reliability upon reviewing the Toshiba Semiconductor Reliability Handbook ("Handling Precautions"/Derating Concept and Methods) and individual reliability data (i.e. reliability test report and estimated failure rate, etc).

Unit: mm



Weight: 0.023 g (typ.)

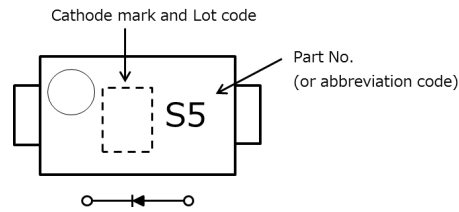
Electrical Characteristics (Ta = 25°C)

Characteristics	Symbol	Test Condition	Min	Typ.	Max	Unit
Peak forward voltage	$V_{FM} (1)$	$I_{FM} = 1\text{ A}$	—	0.35	—	V
	$V_{FM} (2)$	$I_{FM} = 3\text{ A}$	—	0.40	—	
	$V_{FM} (3)$	$I_{FM} = 5\text{ A}$	—	0.43	0.45	
Repetitive peak reverse current	$I_{RRM} (1)$	$V_{RRM} = 5\text{ V}$	—	6	—	μA
	$I_{RRM} (2)$	$V_{RRM} = 30\text{ V}$	—	65	800	
Junction capacitance	C_j	$V_R = 10\text{ V}, f = 1\text{ MHz}$	—	330	—	pF
Thermal resistance	$R_{th} (j-a)$	Device mounted on a ceramic board board size: 50 mm × 50 mm soldering land: 2 mm × 2 mm board thickness: 0.64 mm	—	—	60	°C/W
		Device mounted on a glass-epoxy board board size: 50 mm × 50 mm soldering land: 6 mm × 6 mm board thickness: 1.6 mm	—	—	135	
	$R_{th} (j-l)$	—	—	—	16	

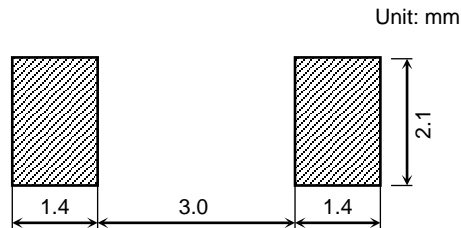
Start of commercial production
 2000-07

Marking

Abbreviation Code	Part No.
S5	CMS05

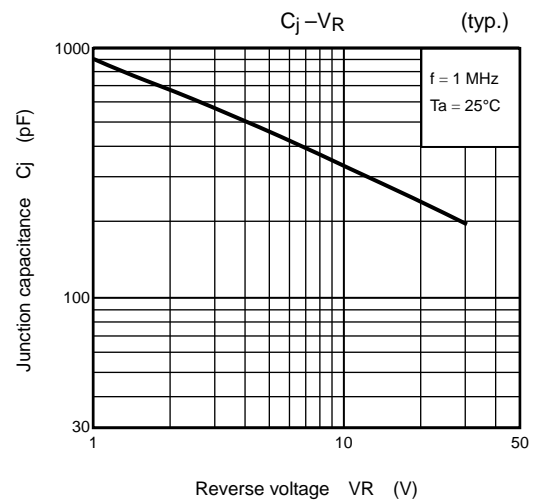
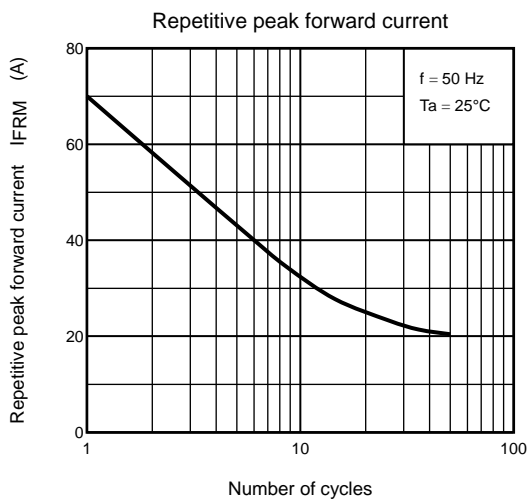
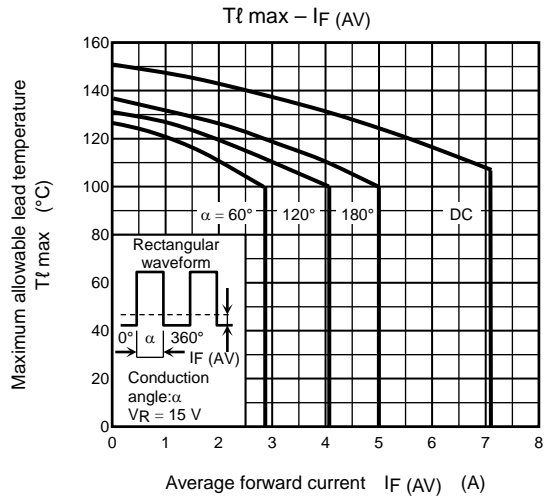
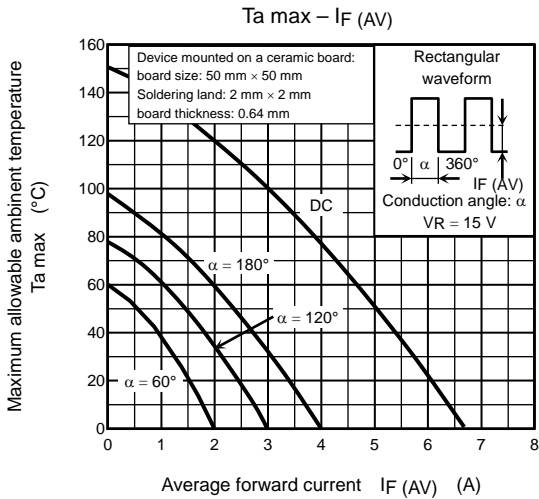
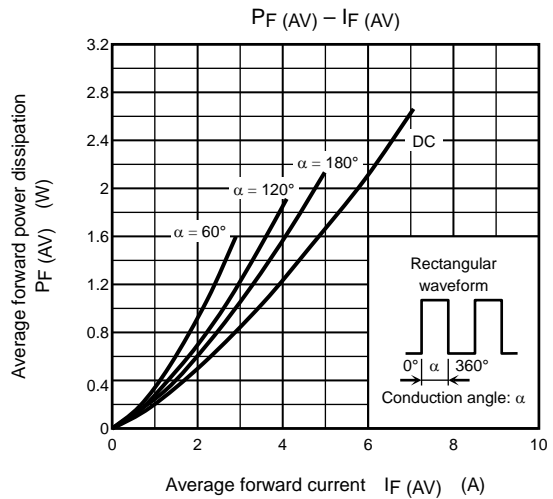
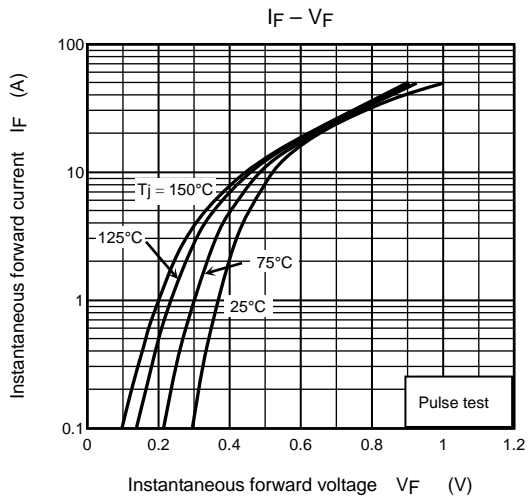


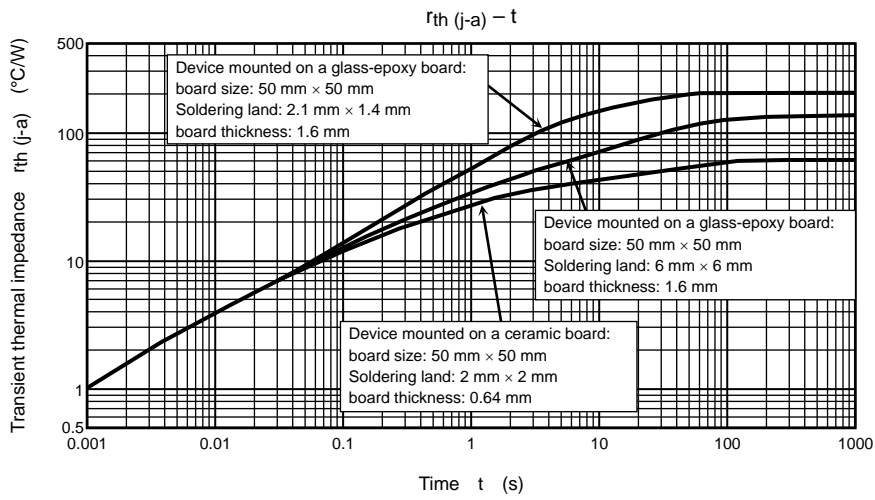
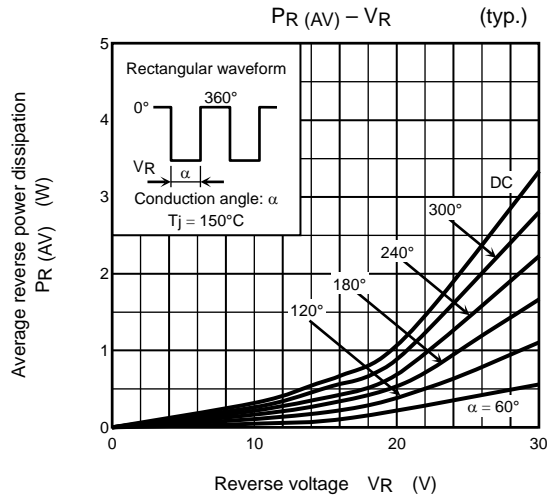
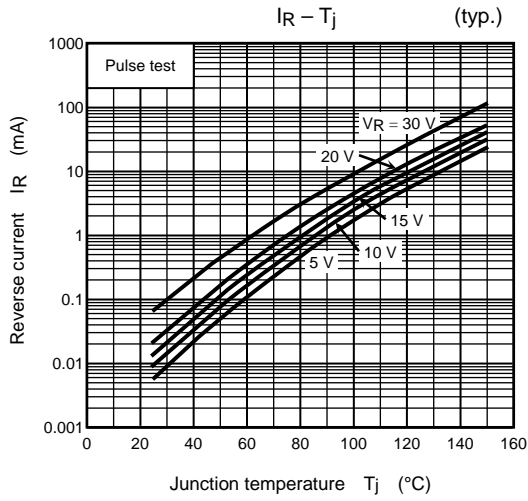
Land pattern dimensions for reference only



Handling Precaution

- Schottky barrier diodes (SBDs) have reverse current greater than other types of diodes. This makes SBDs more vulnerable to damage due to thermal runaway under high-temperature and high-voltage conditions. Thus, both forward and reverse power losses of SBDs should be considered for thermal and safety design.
- The absolute maximum ratings are rated values that must not be exceeded during operation, even for an instant. The following are the recommended general derating methods for designing a circuit board using this device.
 - V_{RRM} : Use this rating with reference to 1) above. V_{RRM} has a temperature coefficient of 0.1%/°C at low temperatures. Take this coefficient into account when designing a circuit board that will be operated in a low-temperature environment.
 - $I_{F(AV)}$: We recommend that the worst-case current be no greater than 80% of the absolute maximum rating of $I_{F(AV)}$ and that the worst-case junction temperature, T_j , be kept below 120°C. When using this device, allow margins, referring to the $T_{a(max)}-I_{F(AV)}$ curve.
 - I_{FSM} : This rating specifies peak non-repetitive forward surge current. This only applies to an abnormal operation, which seldom occurs during the lifespan of a device.
 - T_j : Derate device parameters in proportion to this rating in order to ensure high reliability. We recommend that the junction temperature (T_j) of a device be kept below 120°C.
- Thermal resistance (junction-to-ambient) varies with the mounting conditions of a device on a circuit board. An appropriate thermal resistance value should be used, considering the heatsink, circuit board design and land pattern dimensions (provided for reference only).
- For other design considerations, see the Rectifiers databook or the Toshiba website.





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